

ABSTRACT

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SUBSTRATE MARKING PROCESS

The present substrate marking process can produce markings of small dimensions without damaging the underlying substrate. A substrate is first preconditioned to remove any moisture from its surface to be marked. A coating mixture containing plate resin and thinner is coated onto the substrate surface. The substrate is baked in an oven to harden the coating mixture. Once hardened, a laser is used to etch the markings on the surface of the hardened mixture.

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